

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of: )  
CHEN et al. ) Group Art Unit: 3744  
Application No: 10/712,708 )  
Filed: November 12, 2003 ) Examiner: Ciric, L.  
For: HEAT DISSIPATION MODULE ) Docket No:JLINP174/TLC  
)

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Honorable Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated October 6, 2006, the term to respond extends to January 8, 2007. Also, this is in response to the Notice of Non-Compliant Amendment dated Oct. 4, 2007, the due date extending to Nov. 4, 2007. Please enter this amendment and remarks.

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Abstract** begin on page 6 of this paper.

**Amendments to the claims** are reflected in the listing of claims which begin on page 7 of this paper.

**Remarks/Arguments** begin on page 11 of this paper.